

Telecoil-antennas Inductors

PAS1225V-SERIES

1. Features

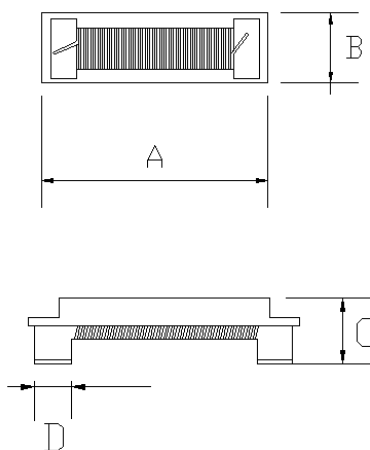
1. Hearing Aid Compatibility-/Telecoil-antennas;
2. PAS1225V-series realizes small size and low profile. 11.6x3.8x2.5mm.
3. 100% Lead (Pb) & Halogen-Free and RoHS compliant.
4. Meets the T3/T4 FCC requirements (HAC) . ANSI C63.19
5. High reliability -Reliability tests comply with AEC-Q200
6. Operating temperature -55~+125°C (Including self - temperature rise)



2. Applications

1. T-coil/HAC-coil for hearing and aid compatible cell phones.
2. Decoupling in RF and IF-circuit.
3. Transponder antenna.

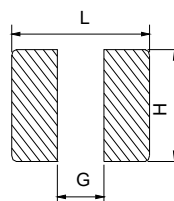
3. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)
PAS1225V	11.6±0.3	3.8±0.3	2.5±0.3	1.50 ref.

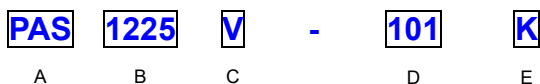
Unit:mm

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
11.6	8.0	3.6

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Category Code
 - D: Inductance
 - E: Inductance Tolerance
- L x H
V=Vehicle
101=100uH
K=±10% , J=±5%

5. Specification

Part Number	Inductance (uH)	Test Frequency (Hz)	Q min.	RDC (Ω)max.	Rated current (mA) max.	SRF (MHz) min.
PAS1225V-101K	100±10%	0.1V/125K	20	3	300	20.0
PAS1225V-201K	200±10%	0.1V/125K	20	6	200	2.00
PAS1225V-492J	4900±5%	0.1V/125K	20	50	50	0.34
PAS1225V-722J	7200±5%	0.1V/125K	40	40	50	0.30

Telecoil-antennas Inductor

PAS6420V-SERIES

1. Features

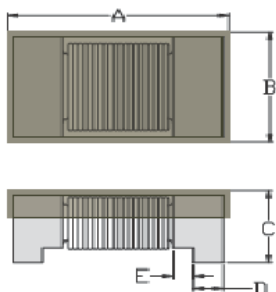
1. Hearing Aid Compatibility-/Telecoil-antennas;
2. PAS6420V-series realizes small size and low profile. 6.4x2.3x2.0 mm.
3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
4. Meets the T3/T4 FCC requirements(HAC-Act) acc. ANSI C63.19
5. High reliability -Reliability tests comply with AEC-Q200
6. Operating temperature -55~+125°C (Including self - temperature rise)



2. Applications

1. T-coil/HAC-coil for hearing and aid compatible cell phones.
2. Decoupling in RF and IF-circuit.
3. Transponder antenna.

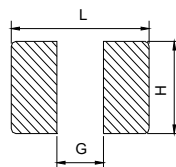
3. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
PAS6420V	6.4±0.3	2.3±0.2	1.8±0.2	0.9 ref.	0.5 ref.

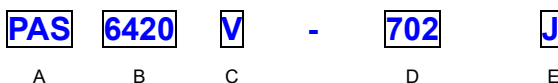
Unit:mm

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
7.0	4.6	2.0

4. Part Numbering



- A: Series
 - B: Dimension
 - C: Category Code
 - D: Inductance
 - E: Inductance Tolerance
- L x H
 - V=Vehicle
 - 702=7000 uH
 - K=±10%, J=±5%

5. Specification

Part Number	Inductance (uH)	f _{L0} (kHz)	SRF KHz(min)	RDC(Ω) MAX	Rated current (mA)Max.
PAS6420V-522J	5200±5%	125	520	113	30
PAS6420V-622J	6200±5%	125	488	123	30
PAS6420V-702J	7000±5%	125	420	125	20
PAS6420V-722K	7200±10%	125	450	130	15

Telecoil-antennas Inductor

PAS8027V-SERIES

1. Features

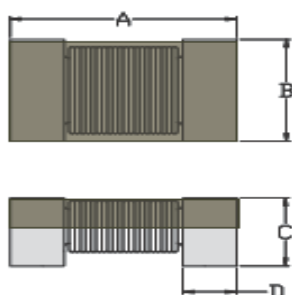
1. Hearing Aid Compatibility-/Telecoil-antennas;
2. PAS8027V-series realizes small size and low profile. 7.85x2.7x2.7 mm
3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
4. Meets the T3 FCC requirements (HAC-Act) acc. ANSI C63.19
5. High reliability -Reliability tests comply with AEC-Q200
6. Operating temperature -55~+125°C (Including self - temperature rise)



2. Applications

4. T-coil/HAC-coil for hearing and aid compatible cell phones .
5. Decoupling in RF and IF-circuit.
6. Transponder antenna.

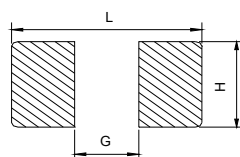
3. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)
PAS8027V	7.85max	2.7max	2.7max	1.15 ref.

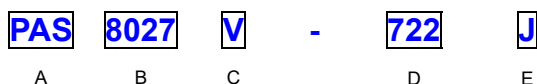
Units : mm

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
9.5	5.2	2.9

4. Part Numbering

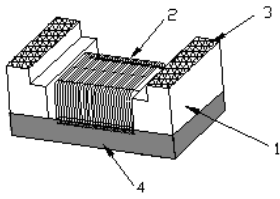


- A: Series
 B: Dimension
 C: Lead Free Code
 D: Inductance
 E: Inductance Tolerance
- V=Vehicle
 722=7.2 mH
 J=±5%

5. Specification

Part Number	Inductance (mH) ±5%	Test Frequency (Hz)	Q Typ.	RDC (Ω) max	Rated current (mA) max.
PAS8027V-452J	4.5	125K	30	80	20
PAS8027V-492J	4.9	125K	30	85	20
PAS8027V-722J	7.2	125K	35	105	20
PAS8027V-193J	18.52	125K	35	240	20

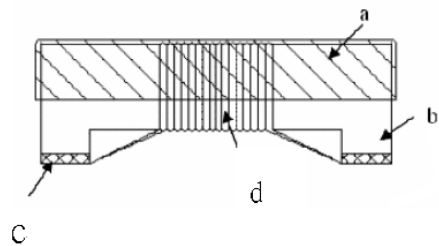
6. Material List (8027V)



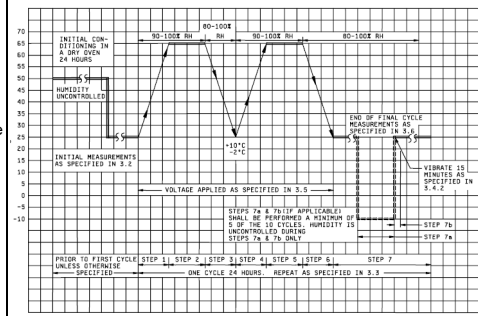
NO	Items	Materials
1	Core	Ferrite
2	Wire	Copper Wire
3	Terminal	Ag/Ni/Sn
4	Adhesive	UV or Epoxy

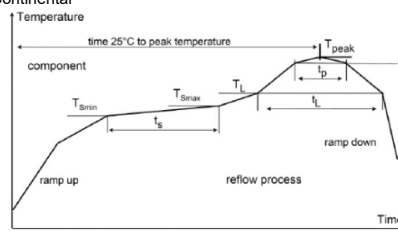
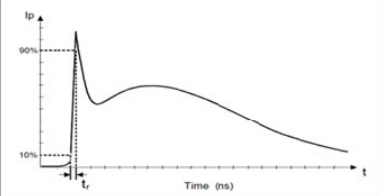
6. Material List (1225V / 6420V)

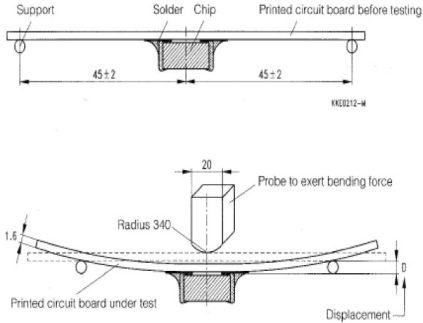
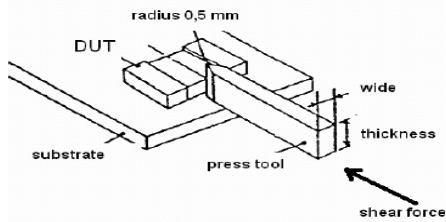
No.	Description	Specification
a.	Upper Plate	UV Glue
b.	Core	Ferrite Core
c.	Termination	Ag/Ni/Sn
d.	Wire	Enameled Copper Wire



7. Reliability and Test Condition

Item	Performance	Test Condition															
Operating temperature	-55~+125°C (Including self - temperature rise)																
Storage temperature	-55+125°C (on board)																
Electrical Performance Test																	
Inductance L	Refer to standard electrical characteristic list	Agilent E4991A , Keysight E4991B ,Keysight 4980AL															
Q		Agilent-4287, Agilent-4285															
SRF		Agilent E4991A , Keysight E4991B															
DC Resistance		Agilent-34420A Agilent-4338B															
Rated Current		Applied the current to coils, the inductance change shall be less than 20% to initial value.															
Reliability Test																	
High Temperature Exposure(Storage) AEC-Q200		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : 125±2°C Duration : 1000hrs Min. Measured at room temperature after placing for 24±4 hrs.															
Temperature Cycling AEC-Q200		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -55±2°C 30min Min. Step2 : 125±2°C transition time 1min MAX. Step3 : 125±2°C 30min Min. Step4 : Low temp. Transition time 1min MAX. Number of cycles : 1000 Measured at room temperature after placing for 24±4 hrs.															
Moisture Resistance (AEC-Q200)	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	t=24 hours/cycle. Note: Steps 7a & 7b not required. Unpowered. Measurement at 24±2 hours after test conclusion. 															
Biased Humidity (AEC-Q200)		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity : 85±3% R.H. Temperature : 85°C±2°C Duration : 1000hrs Min. Measured at room temperature after placing for 24±4hrs															
High Temperature Operational Life (AEC-Q200)		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : 125±2°C Duration : 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±4hrs															
External Visual	Appearance : No damage.	Inspect device construction, marking and workmanship. Electrical Test not required.															
Physical Dimension	According to the product specification size measurement	According to the product specification size measurement															
Resistance to Solvents		Add aqueous wash chemical - OKEM clean or equivalent.															
Mechanical Shock	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (V)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> <tr> <td>Lead</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> </tbody> </table> <p>3 shocks in each direction along 3 perpendicular axes. (18 shocks).</p>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec	SMD	100	6	Half-sine	12.3	Lead	100	6	Half-sine	12.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec													
SMD	100	6	Half-sine	12.3													
Lead	100	6	Half-sine	12.3													

Item	Performance	Test Condition																																																				
Vibration		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency : 10Hz~2KHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude : 5g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)																																																				
Resistance to Soldering Heat	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Test condition : <table border="1" data-bbox="938 434 1417 546"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> <td>1</td> </tr> </tbody> </table> Depth: completely cover the termination Continental  <table border="1" data-bbox="932 864 1407 1039"> <thead> <tr> <th>Component Size</th> <th>Ramp up to 150°C</th> <th>T_{max}</th> <th>t_L</th> <th>T_{max}</th> <th>T_L</th> <th>t_L</th> <th>T_{max}**</th> <th>t_L**</th> <th>time 25°C to peak</th> <th>Ramp down</th> </tr> </thead> <tbody> <tr> <td>Thickness < 1.5mm or 1.5mm-2.5mm and Volume < 350 mm³</td> <td>3.0±0.1°C/s</td> <td>≥190°C</td> <td>≥110s</td> <td>≥200°C</td> <td>≥217°C</td> <td>≥90s</td> <td>≥250°C</td> <td>≥45s</td> <td>≥300s</td> <td>6.0±0.1°C/s</td> </tr> <tr> <td>Thickness 1.5mm-2.5mm and Volume 350-2000 mm³ or Thickness > 2.5mm and Volume < 350 mm³</td> <td>(The component shall be specified for usage in serial production with up to 3.0°C/s)</td> <td>≥190°C</td> <td>≥110s</td> <td>≥200°C</td> <td>≥217°C</td> <td>≥90s</td> <td>≥250°C</td> <td>≥45s</td> <td>≥300s</td> <td>6.0±0.1°C/s</td> </tr> <tr> <td>Thickness 1.5mm-2.5mm and Volume > 2000 mm³ or Thickness > 2.5mm and Volume > 350 mm³</td> <td></td> <td>≥190°C</td> <td>≥110s</td> <td>≥200°C</td> <td>≥217°C</td> <td>≥90s</td> <td>≥245°C</td> <td>≥45s</td> <td>≥300s</td> <td>6.0±0.1°C/s</td> </tr> </tbody> </table> Table 1: Minimum requirements for lead-free soldering *peak temperature is measured on the centre top of the component package ** t _L measured @ T _{peak} -5°C	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1	Component Size	Ramp up to 150°C	T _{max}	t _L	T _{max}	T _L	t _L	T _{max} **	t _L **	time 25°C to peak	Ramp down	Thickness < 1.5mm or 1.5mm-2.5mm and Volume < 350 mm ³	3.0±0.1°C/s	≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥250°C	≥45s	≥300s	6.0±0.1°C/s	Thickness 1.5mm-2.5mm and Volume 350-2000 mm ³ or Thickness > 2.5mm and Volume < 350 mm ³	(The component shall be specified for usage in serial production with up to 3.0°C/s)	≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥250°C	≥45s	≥300s	6.0±0.1°C/s	Thickness 1.5mm-2.5mm and Volume > 2000 mm ³ or Thickness > 2.5mm and Volume > 350 mm ³		≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥245°C	≥45s	≥300s	6.0±0.1°C/s
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles																																																			
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1																																																			
Component Size	Ramp up to 150°C	T _{max}	t _L	T _{max}	T _L	t _L	T _{max} **	t _L **	time 25°C to peak	Ramp down																																												
Thickness < 1.5mm or 1.5mm-2.5mm and Volume < 350 mm ³	3.0±0.1°C/s	≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥250°C	≥45s	≥300s	6.0±0.1°C/s																																												
Thickness 1.5mm-2.5mm and Volume 350-2000 mm ³ or Thickness > 2.5mm and Volume < 350 mm ³	(The component shall be specified for usage in serial production with up to 3.0°C/s)	≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥250°C	≥45s	≥300s	6.0±0.1°C/s																																												
Thickness 1.5mm-2.5mm and Volume > 2000 mm ³ or Thickness > 2.5mm and Volume > 350 mm ³		≥190°C	≥110s	≥200°C	≥217°C	≥90s	≥245°C	≥45s	≥300s	6.0±0.1°C/s																																												
Thermal shock (AEC-Q200)		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1 : -55±2°C 15±1min Step2 : 125±2°C within 20Sec. Step3 : 125±2°C 15±1min Number of cycles : 300 Measured at room temperature after placing for 24±4hrs.																																																				
ESD	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	 Direct Contact and Air Discharge PASSIVE COMPONENT HBM ESD Discharge Waveform to a Coaxial Target Test method : AEC-Q200-002 Test mode : Contact Discharge Discharge level : 4 KV (Level: 2)																																																				
Solderability	More than 95% of the terminal electrode should be covered with solder	a. Method B, 4hrs @155°C dry heat @235°C±5°C Testing Time : 5 +0/-0.5 seconds b. Method D category 3. (8hours ± 15 min)@ 260°C±5°C Testing Time : 30 +0/-0.5 seconds																																																				
Electrical Characterization	Refer Specification for Approval	Summary to show Min, Max, Mean and Standard deviation .																																																				
Flammability	Electrical Test not required.	V-0 or V-1 are acceptable.																																																				

Item	Performance	Test Condition
<p style="text-align: center;">Board Flex</p>	<p>Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value</p>	<p>Preconditioning: Run through reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board.</p> 
<p style="text-align: center;">Terminal Strength(SMD)</p>	<p>Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value</p>	<p>Preconditioning: Run through reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.</p> 

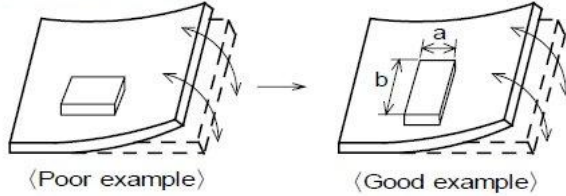
8. Soldering and Mounting

8-1. Attention regarding P.C.B. bending

The following shall be considered when designing P.C.B.'S

(1)P.C.B. shall be designed so that products are not subjected to the mechanical stress for board warpage.

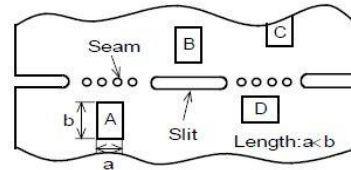
<Products direction>



Products shall be located in the sideways direction (Length: $a < b$) to against the mechanical stress.

(2) Products location on P.C.B.

Products (A,B,C,D) shall be located carefully to prevent mechanical stress when warping the board.
Products may be subjected to the mechanical stress in the order of $A > C > B \approx D$.



Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2.1 Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

8-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow

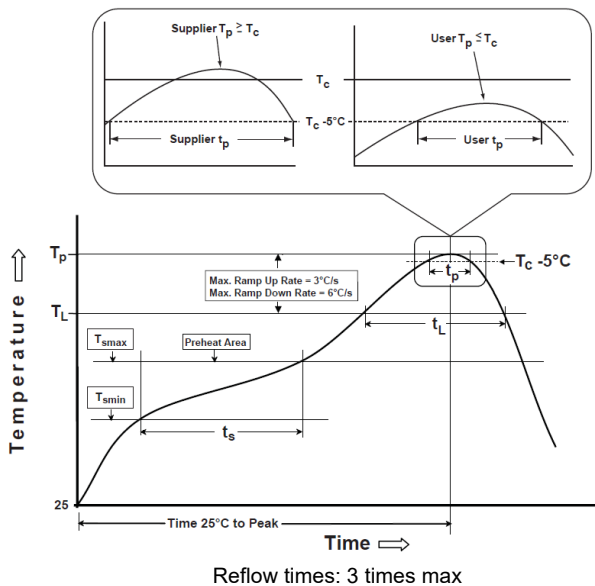


Fig.2 Iron soldering temperature profiles

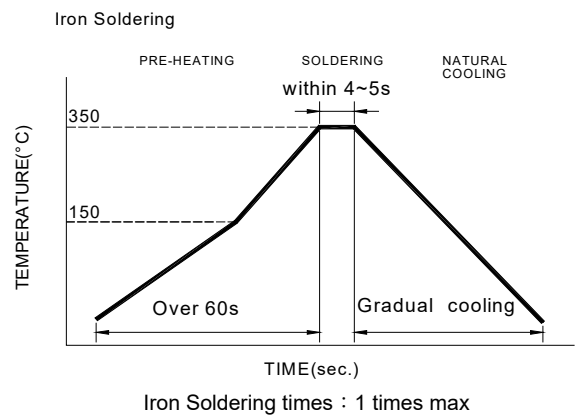


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	150°C 200°C 60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217°C 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate(T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p: maximum peak package body temperature, **T_c**: the classification temperature.

For user (customer) **T_p** should be equal to or less than **T_c**.

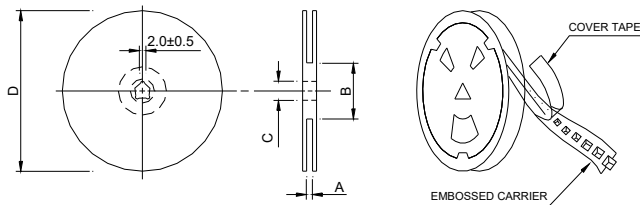
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ◦

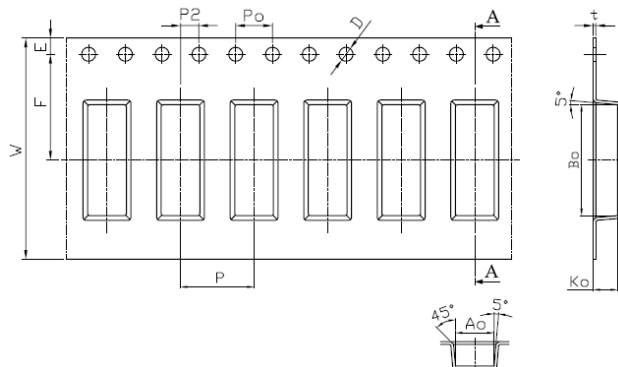
9. Packaging Information

9-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.0±0.5	100.0±2.0	13.5±0.5	330

9-2 Tape Dimension

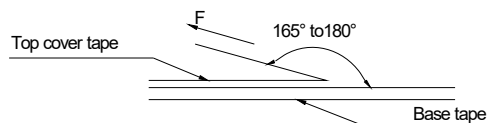


Series	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	P0(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)
PAS1225	24.00±0.3	8.00±0.1	1.75±0.1	11.50±0.1	2.00±0.1	1.50+0.1/-0	4.00±0.1	4.20±0.1	12.05±0.1	2.65±0.1	0.35±0.05

9-3. Packaging Quantity

Chip size	1225
Reel	1000
Reel Size	13"x24mm

9-4. Tearing Off Force



The force for tearing off cover tape is 10 to 80 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard).

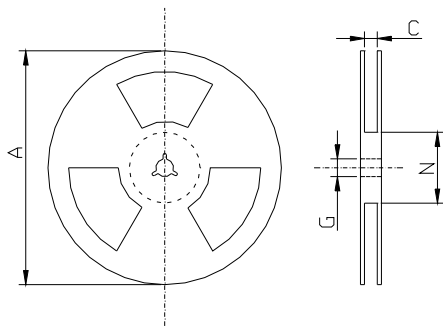
Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
 - To maintain the solderability of terminal electrodes:
 1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
 3. Recommended products should be used within 12 months from the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

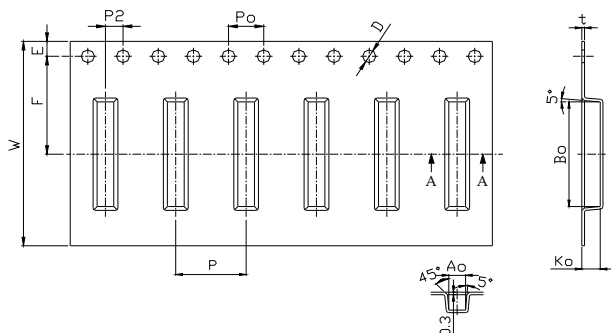
9. Packaging Information

9-1. Reel Dimension



Type	A(mm)	C(mm)	G(mm)	N(mm)
7"x16mm	180.0±2.0	16.5±1.0	13.5±0.5	100.0±2.0

9-2. Tape Dimension / 16mm

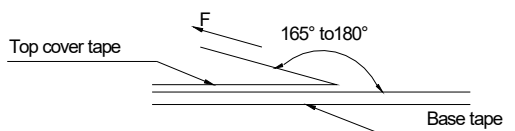


9-3. Packaging Quantity

Chip size	6420
Reel	1000
Reel Size	7"x16mm

Series	Size	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)	t(mm)
PAS	6420	8.0±0.1	4.0±0.1	2.0±0.1	6.7±0.10	2.5±0.10	2.2±0.10	0.3±0.05
Series	Size	D(mm)	E(mm)	F(mm)	W(mm)			
PAS	6420	1.5+0.1/-0	1.75±0.1	7.5±0.1	16±0.30			

9-4. Tearing Off Force



The force for tearing off cover tape is 10 to 80 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

• Storage Conditions

To maintain the solderability of terminal electrodes:

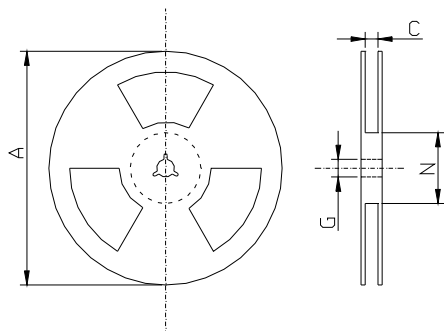
1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months from the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

• Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

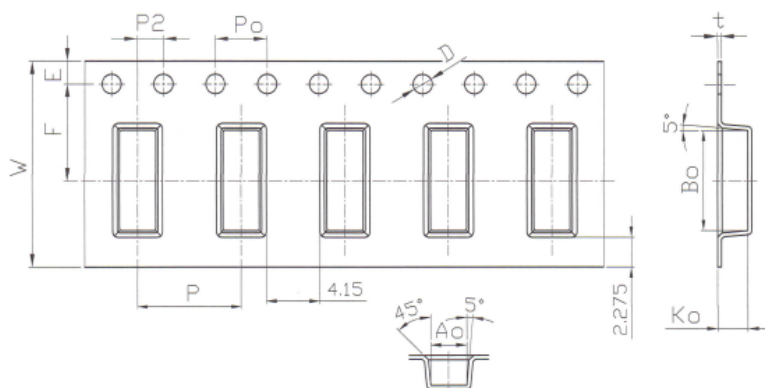
9. Packaging Information

9-1. Reel Dimension



Type	A(mm)	C(mm)	G(mm)	N(mm)
7"x16mm	180.0±2.0	16.5±1.0	13.5±0.5	100.0±2.0

9-2. Tape Dimension / 16mm

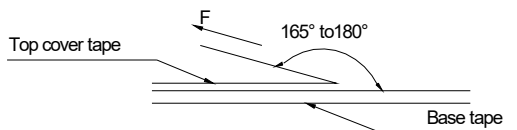


9-3. Packaging Quantity

Chip size	8027
Reel	1000
Reel Size	7"x16mm

Series	Size	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)	t(mm)
PAS	8027	8.0±0.1	4.0±0.1	2.0±0.1	7.9±0.10	2.8±0.10	2.35±0.10	0.3±0.05
Series	Size	D(mm)	E(mm)	F(mm)	W(mm)			
PAS	8027	1.5+0.1/-0	1.75±0.1	7.5±0.1	16±0.30			

9-4. Tearing Off Force



The force for tearing off cover tape is 10 to 80 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300

Application Notice

• Storage Conditions

To maintain the solderability of terminal electrodes:

1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months from the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

• Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.